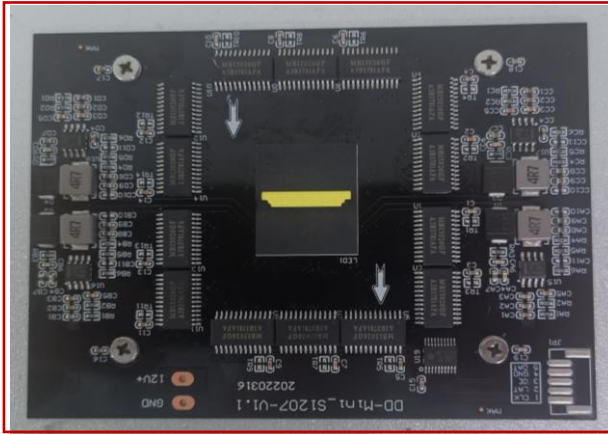
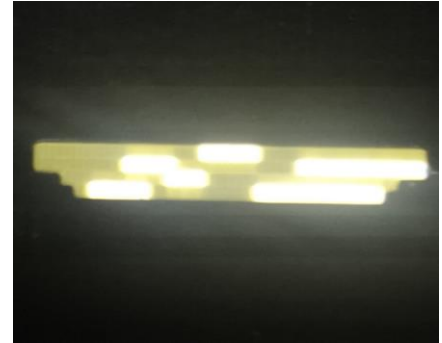


S1207 with driving circuit



lighting of S1207



Main Features

Highly reliable flip chip welded on high-precision multilayer ceramic circuit board through zero void welding technology;

Flip-chips are close arranged to facilitate optical design and one flip chip corresponds to one independent pixel totaling 204 pixels. The luminous area of each pixel corresponds to the size of flip-chip about 0.51 x 0.72mm. The minimum size of flip-chip can be as small as 0.1x0.2mm;

A white wall with high reflectivity around each flip-chip blocks side lights to avoid cross-interference of lighting between flip-chips;

The maximum driving current of each pixel can reach 300mA and generate light of no less than 75 lumens at room temperature and the total power can reach 180W;

The high-precision multilayer ceramic circuit board is reflow welded on the PCB as the driving IC carrier plate. With the high thermal conductivity and high insulation of the ceramic substrate, an effective thermoelectric separation mechanism can be realized, so that the heat generated by the LED light source can be quickly transmitted to the radiator, to ensure that the LED light source can work at a suitable temperature, which not only improves the luminous efficiency, reduces the light attenuation, but also improves the reliability of the device.